



N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	Rds(on) Max	I _D Max T _A = +25°C
	12mΩ @ V _{GS} = 10V	10A
30V	16mΩ @ V _{GS} = 4.5V	8.5A

Description and Applications

This MOSFET is designed to minimize the on-state resistance (RDS(ON)) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Battery Management Application
- Power Management Functions
- DC-DC Converters

Features and Benefits

- 0.6mm Profile Ideal for Low Profile Applications
- PCB Footprint of 4mm²
- Low Gate Threshold Voltage
- Low On-Resistance
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e.: parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please refer to the related automotive grade (Q-suffix) part. A listing can be found at

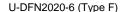
https://www.diodes.com/products/automotive/automotive-products/.

 This part is qualified to JEDEC standards (as references in AEC-Q) for High Reliability.

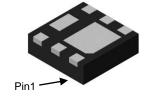
https://www.diodes.com/quality/product-definitions/

Mechanical Data

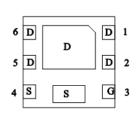
- Case: U-DFN2020-6
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (4)
- Weight: 0.0065 grams (Approximate)



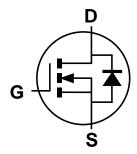




Top View Bottom View



Pin Out Bottom View



Equivalent Circuit

Ordering Information (Note 4)

Part Number	Case	Packaging
DMN3016LFDF-7	U-DFN2020-6 (Type F)	3,000/Tape & Reel
DMN3016LFDF-13	U-DFN2020-6 (Type F)	10,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.



Marking Information

Site 1



NZ = Product Type Marking Code YM = Date Code Marking Y = Year (ex: G = 2019) M = Month (ex: 9 = September)

Date Code Kev

Year	2017	20	18	2019	2020	20	21	2022	2023	20	24	2025
Code	E	F	=	G	Н		I	J	K		_	М
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D

Site 2



NZ = Product Type Marking Code YWX = Date Code Marking Y = Year (ex: 9 = 2019) W = Week (ex: a = Week 27; z Represents Week 52 and 53) X = Internal Code (ex: U = Monday)

Date Code Key

Year	2019	2020	2021	2022	2023	2024	2025	2026
Code	9	0	1	2	3	4	5	6

Week	1-26	27-52	53
Code	A-Z	a-z	z

Internal Code	Sun	Mon	Tue	Wed	Thu	Fri	Sat
Code	Т	U	V	W	X	Y	Z



Maximum Ratings (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage	VDSS	30	V		
Gate-Source Voltage			Vgss	±20	V
	Steady	T _A = +25°C	L -	10	٨
	State	T _A = +70°C	- I _D	8	А
Continuous Drain Current (Note 6) V _{GS} = 10V		T _A = +25°C	I _D	12	^
	t<10s	T _A = +70°C		9	Α
Maximum Continuous Body Diode Forward Current	(Note 6)		ls	2.5	Α
Pulsed Drain Current (10μs Pulse, Duty Cycle = 1%	I _{DM}	50	Α		
Avalanche Current (Note 7) L = 0.1mH		lar	22	Α	
Avalanche Energy (Note 7) L = 0.1mH			Ear	24	mJ

Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

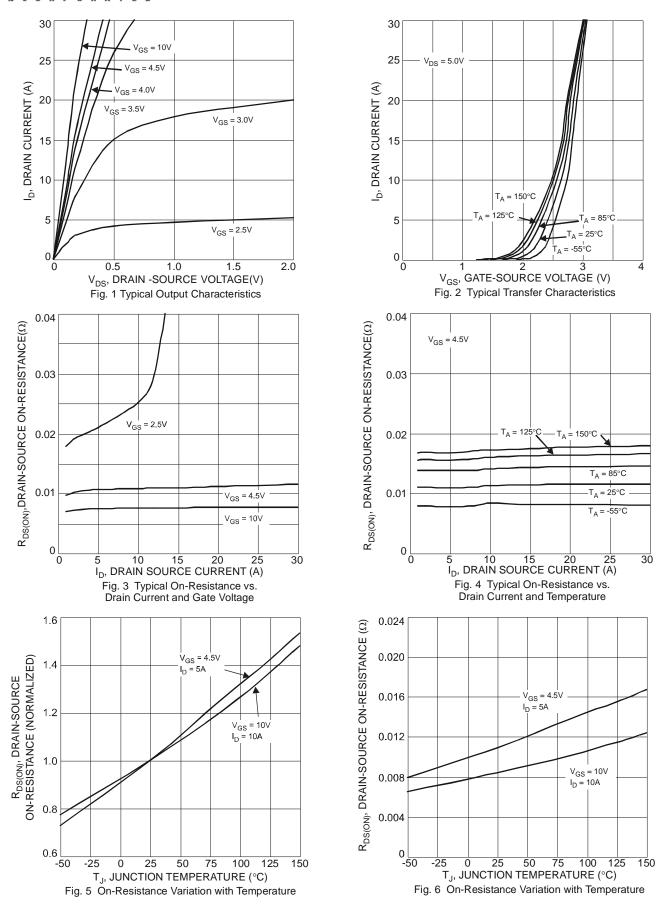
Characteristic		Symbol	Value	Unit	
Total Power Dissination (Note 5)	$T_A = +25$ °C	D-	0.73	W	
Total Power Dissipation (Note 5)	T _A = +70°C	PD	0.47	VV	
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	D	174	°C/W	
memai Resistance, Junction to Ambient (Note 5)	t<10s	$R_{\theta JA}$	121		
Total Power Dissipation (Note 6)	$T_A = +25$ °C	PD	2.02	W	
Total Fower Dissipation (Note o)	$T_A = +70$ °C	FD	1.30	V V	
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	р	66	°C/W	
memial Resistance, Junction to Ambient (Note o)	t<10s	$R_{\theta JA}$	42		
Thermal Resistance, Junction to Case (Note 6)	Steady State	$R_{\theta JC}$	11.6		
Operating and Storage Temperature Range		T _{J,} T _{STG}	-55 to +150	°C	

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)				•			
Drain-Source Breakdown Voltage	BV _{DSS}	30	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current	IDSS	_	_	1	μΑ	$V_{DS} = 30V$, $V_{GS} = 0V$	
Gate-Source Leakage	Igss	_	_	±100	nA	$V_{GS} = \pm 20V$, $V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	VGS(TH)	1.4	_	2.0	V	$V_{DS} = V_{GS}$, $I_D = 250\mu A$	
Static Drain-Source On-Resistance	D	_	8	12	mΩ	V _G S = 10V, I _D = 11A	
Static Drain-Source On-Resistance	Rds(on)	_	12	16	1117.5	$V_{GS} = 4.5V, I_{D} = 9A$	
Diode Forward Voltage	V _{SD}	_	0.70	1.0	V	$V_{GS} = 0V$, $I_S = 1A$	
DYNAMIC CHARACTERISTICS (Note 9)			•	•			
Input Capacitance	Ciss	_	1415	_		15)/)/ 0)/	
Output Capacitance	Coss	_	119		pF	$V_{DS} = 15V, V_{GS} = 0V,$ f = 1.0MHz	
Reverse Transfer Capacitance	Crss	_	82	_		1 = 1.01/11/12	
Gate Resistance	Rg	_	2.6	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1.0MHz$	
Total Gate Charge (V _{GS} = 4.5V)	Qg	_	11.3	_			
Total Gate Charge (V _{GS} = 10V)	Qg	_	25.1	_	nC	V 45V L 40A	
Gate-Source Charge	Qgs	_	3.5	_	nc	$V_{DS} = 15V, I_{D} = 12A$	
Gate-Drain Charge	Qgd	_	3.6	_			
Turn-On Delay Time	t _{D(ON)}		4.8	_			
Turn-On Rise Time	t _R	_	16.5	_		V _{DD} = 15V, V _{GS} = 10V,	
Turn-Off Delay Time	tD(OFF)		26.1	_	ns	$R_L = 1.25\Omega$, $R_q = 3\Omega$	
Turn-Off Fall Time	tF	_	5.6	_			
Reverse Recovery Time	trr	_	12.3	_	ns	104 17/14 5004/	
Reverse Recovery Charge	Q _{RR}	_	10.4	_	nC	I _F = 12A, di/dt = 500A/μs	

Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
I_{AS} and E_{AS} ratings are based on low frequency and duty cycles to keep T_J = +25°C.
Short duration pulse test used to minimize self-heating effect.
Guaranteed by design. Not subject to product testing.







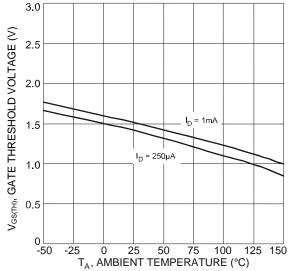
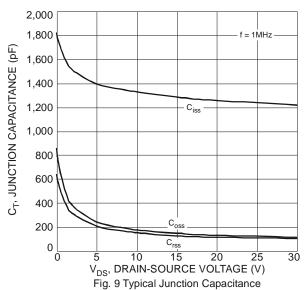
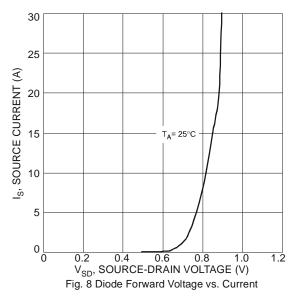
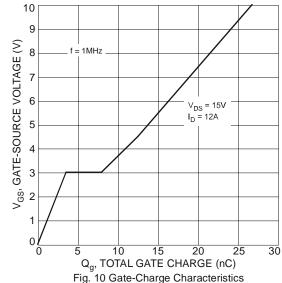


Fig. 7 Gate Threshold Variation vs. Ambient Temperature









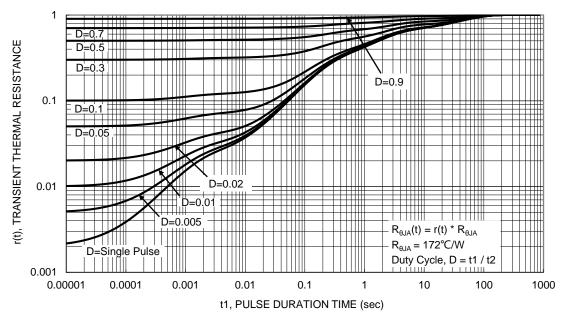


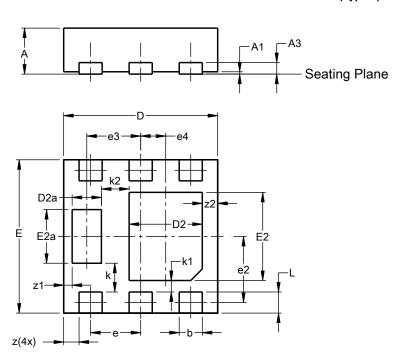
Figure 11. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

U-DFN2020-6 (Type F)

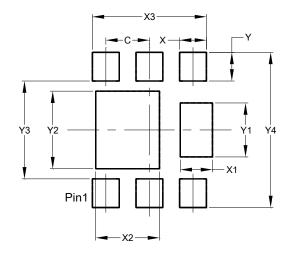


U-DFN2020-6							
(Type F)							
Dim	Min	Min Max Typ					
Α	0.57	0.63	0.60				
A1	0.00	0.05	0.03				
A3	1	-	0.15				
b	0.25	0.35	0.30				
D	1.95	2.05	2.00				
D2	0.85	1.05	0.95				
D2a	0.33	0.43	0.38				
Е	1.95	2.05	2.00				
E2	1.05	1.25	1.15				
E2a	0.65	0.75	0.70				
е		0.65 BS	С				
e2).863 BS	SC				
е3		0.70 BS	С				
e4).325 BS	SC				
k		0.37 BS					
k1		0.15 BS					
k2		0.36 BS					
L		0.325					
Z	0.20 BSC						
z 1	0.110 BSC						
z2		0.20 BS	_				
All C	imens	ions in	mm				

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

U-DFN2020-6 (Type F)



Dimensions	Value			
	(in mm)			
С	0.650			
Χ	0.400			
X1	0.480			
X2	0.950			
Х3	1.700			
Υ	0.425			
Y1	0.800			
Y2	1.150			
Y3	1.450			
Y4	2.300			



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